Product / Process Change Notice

PCN No.: Z200-DM201408-01-B Date : September 4, 2014

Change Title : **W25Q32FW "F-Series" (58nm) to replace W25Q32DW "D-Series" (90nm) 32Mb 1.8V SpiFlash® Memories**

Change Classification: ☑ **Major** ☐Minor
Change item: ☑ **Design** ☐ Raw Material ☐ Wafer FAB ☐ Package Assembly ☐ Testing ☐ Others : _____.

Affected Product(s):

90nm 32Mb "D-Series" SpiFlash memories:
W25Q32DWSSIG, W25Q32DWSTIM, W25Q32DWZPIG

Description of Change(s) :

The W25Q32FW 32Mb 1.8V SpiFlash® Memories use Winbond's 58nm Flash technology. It is function-compatible W25Q32DW 90nm devices offering improved performance, features and availability.

Reason for Change(s) :

1) Technology migration from 90nm to 58nm on 12" wafer.
2) Improved features (see below)

Features

a) Advanced 58nm SpiFlash technology
b) Command compatible with W25Q32DW (same JEDEC Device ID, Superset Instruction Set)
c) Individual Block Write Protection in addition to the existing protection schemes
d) Addition configurable hardware /RESET pin
e) Programmable Output Drive Strength

Benefits

a) 58nm technology allows for imporved availability and best possible pricing
b) Provides drop-in replacement capability for seemless transitions
c) Faster Read Performance

Impact of Change(s) : (positive & negative)

Form: No Change

Fit: No Change

Function: No change

Reliability: No concern (please refer to Attachment I)

Hazardous Substances: No concern (please refer to Attachment II)

Qualification Plan/ Results :

Based on Winbond W25Q32FW Serial Flash Reliability report, the new product meets our criteria and no quality concern (refer to Attachment I in details)

Implementation Plan :

☐ Date Code : _____ onward ☐ Lot No.: _____ onward ☑ Proposed first ship date: Refer to Attachment I

Originator:(QA Sec. Manager)	YH Cheng	***Responsible: (QA Dept. Manager)***	YH Cheng	***Approval:(QRA Director)***	Yu-Sung, Cheng
Contact for Questions & Concerns	Name: Betty Hyhuang TEL:886-3-5678168 (ext.86549) FAX: 886-3-5796124 Address : # 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan E-mail: Hyhuang8@winbond.com				

Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

☐ Approval ☐ Disapproval ☐ Conditional Approval : _____.

Date: _____

Dept. name:_____

Person in charge:_____.

Table 1 the impact product list: Primary Winbond replacement part numbers for 90nm W25Q32DW D-Series products are listed below. These devices offer the best future availability.

Winbond Current PN (90nm D-Series)	Winbond Primary Replacement PN (58nm F-Series)
W25Q32DWSSIG	W25Q32FWSSIG
W25Q32DWSTIM	W25Q32FWSTIQ
W25Q32DWZPIG	W25Q32FWZPIG

Winbond Electronics Corporation
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Taiwan, R.O.C.

Product Obsolescence Notice

W25Q32FW SpiFlash Memories

Notification Date: August 15, 2014

Dear Valued Customer,

This letter is to notify you of Winbond's intention to terminate production of the W25Q32DW SpiFlash memory. And replace it with the W25Q32FW. Current Part Numbers affected and corresponding replacement Part Numbers are listed below.

Winbond Current PN (90nm D-Series)	Winbond Primary Replacement PN (58nm F-Series)
W25Q32DWSSIG	W25Q32FWSSIG
W25Q32DWSTIM	W25Q32FWSTIQ
W25Q32DWZPIG	W25Q32FWZPIG

The W25Q32FW device features:

Features

a) Advanced 58nm SpiFlash technology
b) Command compatible with W25Q32DW (same JEDEC Device ID, Superset Instruction Set)
c) Individual Block Write Protection in addition to the existing protection schemes
d) Addition configurable hardware /RESET pin
e) Programmable Output Drive Strength

Benefits

a) 58nm technology allows for improved availability and best possible pricing
b) Provides drop-in replacement capability for seamless transitions
c) Faster Read Performance

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

90nm Part Number	Notification Date	90nm Last Order Date	90nm Last Ship Date	58nm Part Number	58nm Reliability Report	58nm Mass Production
W25Q32DW	Aug./13/ 2014	Feb./13/ 2015	Aug./13/ 2015	W25Q32FW	Jul./29/ 2014	Jul./29/ 2014

Eddy Hung

Assistant Vice President of Flash Marketing